

### 1.8mm SOLID STATE LAMP

Part Number: WP2060SRD

Super Bright Red

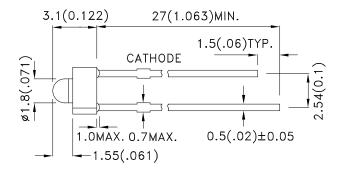
### **Features**

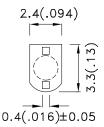
- 1.8mm DIAMETER SMALL SIZE LED LAMP.
- ULTRA BRIGHTNESS IS AVAILABLE.
- RELIABLE AND RUGGED.
- VERSATILE MOUNTING ON P.C. BOARD OR PANEL.
- AVAILABLE IN DIFFUSED LENS.
- RoHS COMPLIANT.

### Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

## **Package Dimensions**





- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
   Specifications are subject to change without notice.





PAGE: 1 OF 6 SPEC NO: DSAH3807 **REV NO: V.2 DATE: DEC/08/2007** APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: R.Chen ERP: 1101002693

## **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP2060SRD	Super Bright Red (GaAlAs)	RED DIFFUSED	70	200	70°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	660		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	IF=20mA
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I=20mA
lR	Reverse Current	Super Bright Red		10	uA	VR = 5V

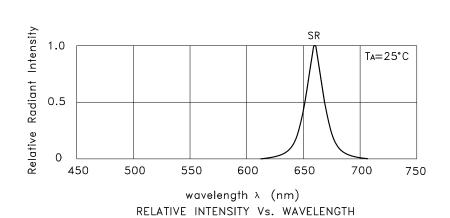
- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

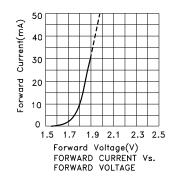
Parameter	Super Bright Red	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	155	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

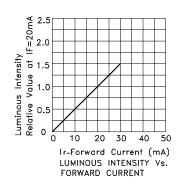
- 1. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 2. 2mm below package base.
- 3. 5mm below package base.

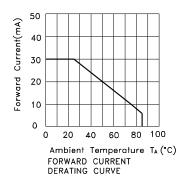
SPEC NO: DSAH3807 **REV NO: V.2** DATE: DEC/08/2007 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: R.Chen ERP: 1101002693

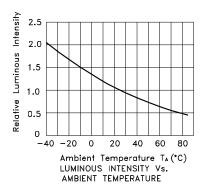


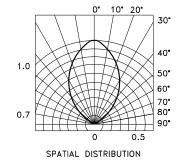
Super Bright Red WP2060SRD





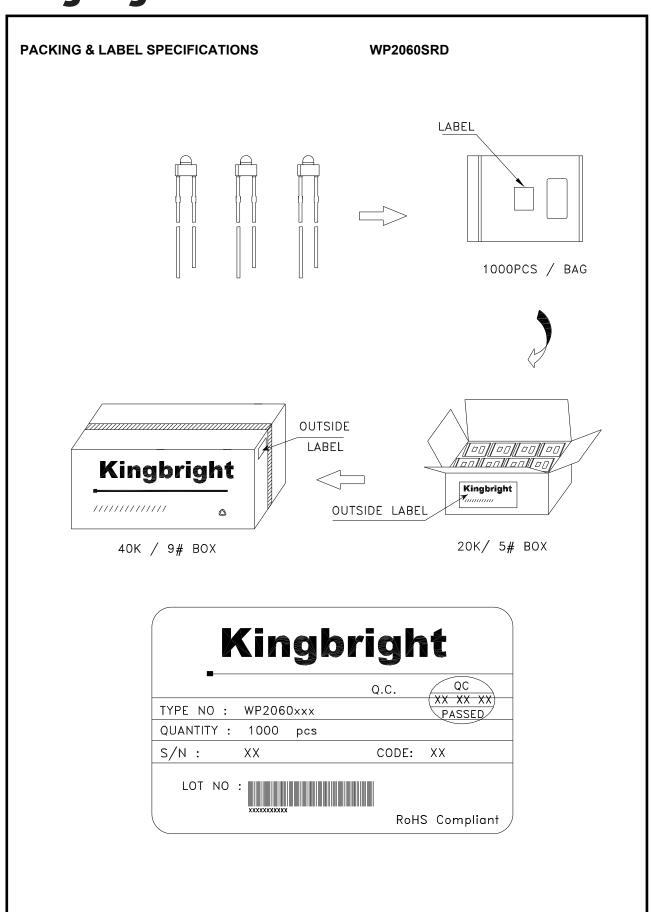






 SPEC NO: DSAH3807
 REV NO: V.2
 DATE: DEC/08/2007
 PAGE: 3 OF 6

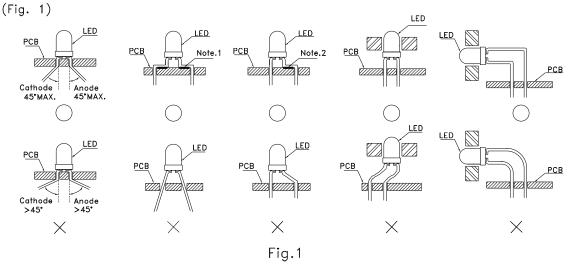
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SPEC NO: DSAH3807 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: DEC/08/2007 DRAWN: R.Chen PAGE: 4 OF 6 ERP: 1101002693

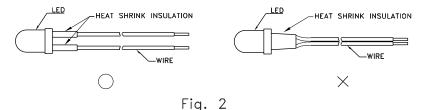
### LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead—forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

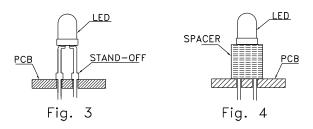


" $\bigcirc$ " Correct mounting method " $\times$ " Incorrect mounting method Note 1-2: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat—shrink tubing to insulate the exposed leads to prevent accidental contact short—circuit. (Fig. 2)



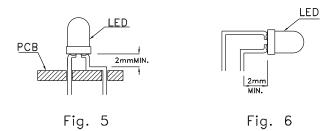
3. Use stand—offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.



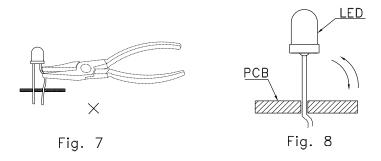
SPEC NO: DSAH3807 REV NO: V.2 DATE: DEC/08/2007 PAGE: 5 OF 6
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: R.Chen ERP: 1101002693

## LEAD FORMING PROCEDURES

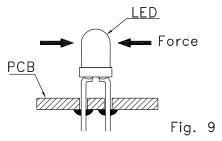
1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead—forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)



6. After soldering or other high—temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



 SPEC NO: DSAH3807
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 PAGE: 6 OF 6

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